SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 0.50mm ZIF FPC Connector, R/A, SMT Type Bottom Contact

CUSTOMER PROD.NO/DWG.NO:

E&T PROD.NO:

6707K-XXXX-XXX

APPROVAL SHEET NO:

E&T DWG. NO./DOCUMENT: 6707K-XXXX-XXX

REV: A3

PLEASE RETURN TO US ONE COPY OF"SPECIFICATION FOR APPROVAL"WITH YOUR APPROVED SIGNATURES.

APPROVED S	SIGNATURES	



ENTERY INDUSTRIAL CO., LTD. E&T ELECTRONICS (DONG GUAN) CO., LTD. E&T ELECTRONICS (SU ZHOU) CO., LTD. E&T ELECTRONICS (NANKEEN)CO.,LTD.

Title : Pitch 0.50mm ZIF FPC Connector, R/A, SMT Type Bottom Contact

100100000000000000000000000000000000000	ELEASE STORY	Title: Pitch	0.50mm ZIF FPC Connector, R/A, SMT	Type Bottom Contact
A3	05,31,2012'		Document Contains Information That Is And Should Not Be Used Without Writ	
Rev Document	Description	E&I	Prepared By: Josh Lee	Date: 01,27,2007'
6	707K-XXX	X-XXX	Checked By:	Date: 16 2 -10/2
Ŭ	, , , is initially		Approved By:	Date:

GROUP AND TEST SEQUENCE

	Test of Examination				,	Test	t Gr	oup)			
	Test of Examination	А	В	С	D	Е	F	G	Η	Ι	J	Κ
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,4	1,5	1,3	1,3	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	FPC Retention Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						3		2			
13	Resistance To Soldering Heat									2		
14	Steam Aging						2					
15	Salt Spray							3				
16	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE :

This specification covers the pitch 0.5 mm ZIF FPC connector series.

2. PRODUCT NAME AND PART NUMBER :

Product Name	E&T Part Number
0.50mm ZIF FPC Connector, R/A, SMT Type Bottom Contact	6707K-XXXX-XXX

3. RATINGS :

Item	S	tandard
Rated Voltage (MAX.)	50 V	DC
Rated Current (MAX.)	0.5A	DC
Operating Temperature Range	-40 ⁰	C ~ +80 ⁰ C

*Including terminal temperature rise

4.PERFORMANCE :

4-1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 1 mA Max. Test Voltage: 20mV Max Test Method:EIA-364-06B	50 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 100V DC. Test Duration: 1 minutes.	Initial: 500 MΩ Min
	Resistance	Test Method:EIA-364-21C	Final: 100 MΩ Min.
4-1-3	Dielectric Strength	Test Voltage: 200V AC. Test Time: 60 sec. Test Method:EIA-364-09C	No Breakdown

4-2 Mechanical Performance

	Item	Test Condition	Requirement
4-2-1	FPC Retention Force	Test Speed: 25±3 mm/min. Test Method:EIA-364-38B	0.015kgf (per pin) MIN
4-2-3	Terminal / Housing Retention Force	Test Speed: 25mm/min.	0.3kgf (Min)

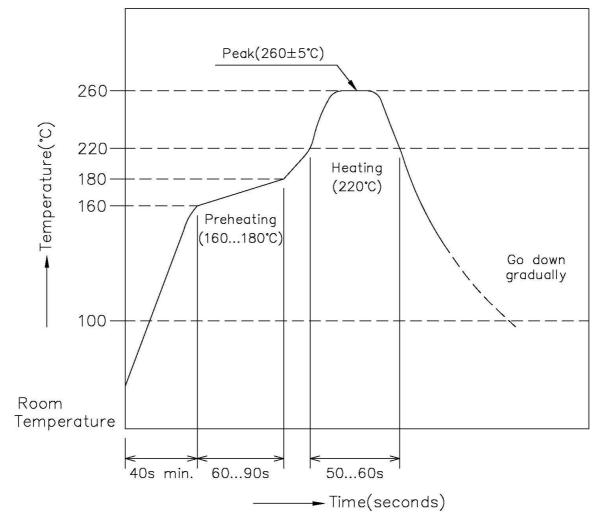
4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Insert and withdraw actuator up to 20cycles at the speed rate of less than 10 cycles/	Contact Re	sistance
4-3-1	Durability	minute.	Initial Value	\leq 50 m Ω
		Test Method:EIA-364-09C	Final Value	$\leq 80 \text{ m}\Omega$
		Amplitude : 1.5 mm Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-2	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method:EIA-364-28D	Contact Resistance	\leq 80 mΩ
			Discontinuity	1µsec
4-3-4	Heat	Temperature: 80±2℃ Duration: 96 hours	Appearance	No Damage
4-0-4	Resistance		Contact Resistance	\leq 80 mΩ
4-3-5	Cold	Temperature: -40±2℃ Duration: 96 hours	Appearance	No Damage
4-0-0	Resistance		Contact Resistance	\leq 80 m Ω
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-6	Humidity	Duration: 96 hours Test Method:EIA-364-31B	Contact Resistance	\leq 80 mΩ
+ 0 0	inannaity		Insulation Resistance	\geq 100M Ω
			Dielectric Strength	Must meet 4-1-3

	Item	Test Condition		Requir	rement
4-3-7	Solder Ability	Soldering Time : 3±0.5 sec Solder Temperature : 245±5℃ Test Method:EIA-364-52		Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Resistance To Soldering Heat	Soldering Time : 10±0.5 sec Solder Temperature : 260±5℃ Test Method:EIA-364-56C		Appearance	No Damage
		Steam Aging Temperature : 98±2 Duration: 8 hours Solder Temperature : 235±5°C Soldering Time : 2+0 5 ago	2°C	Appearance	No Damage
4-3-9	Steam Aging	Soldering Time : 3±0.5 sec Test Method:EIA-364-17B		Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-10	Salt Spray	Chamber Temperature : $35\pm2^{\circ}$ C Air Tank Temperature : $47\pm1^{\circ}$ C Salt Solution : $5\pm0.5^{\circ}$ Duration : 48 hours		Appearance	No Damage
	our oplay	Test Method:EIA-364-26B		Contact Resistance	\leq 80 m Ω
4-3-11	Temperature	·· j ····	30 minutes 30 minutes	Appearance	No Damage
	Cycling	c)+ 85 ±2℃ 3 Test Method:EIA-364-31B	30 minutes	Contact Resistance	\leq 80 m Ω

INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At $260\pm5^{\circ}$ C peak shall be 10 seconds maximum.





Sumitomo Chemical Co.,Ltd. Electronic Materials Division

2. Physical, Mechanical and Thermal property

	13	ASTM	Unit	E6007LHF Z	E6807LHF Z	E6808LHF Z	E6808UHF Z	E6810LHF Z
Filler		-	1 2 0.000	GF	GF/mineral	GF/mineral	GF/mineral	GF/mineral
Kind of GF				Chopped	Chopped	Chopped	Milled	Chopped
Filler content	100 640 - 10		%	35	35	40	40	50
Physical prope	erty					1		1
Gravity		D792		1.65	1.67	1.71	1.72	1.84
Water absorptio	on	D570	%	0.02	0.02	0.02	0.02	0.02
Mold shrinkage	e MD	SC method	%	0.26	0.20	0.23	0.22	0.13
	TD	*1	%	0.60	0.73	0.63	1.02	0.38
Mechanical Pr	roperty							
Tensile	strength	D638	MPa	157	135	127	100	105
	elongation		%	5.1	5.3	4.5	5.0	4.0
Flexural	strength	D790	MPa	158	143	146	120	133
6.4mmt	modules	D790	GPa	11.8	10.5	11.8	9.4	12.6
lzod impact str Non-notched	ength	D256	J/m	251	335	302	350	200
TDUL 1.82MPa		D648	°C	269	269	274	240	266
Thermal prop	erty							1
Solder resistan	ce	SC method	°C	305	300	300	290	280
Liner expansion 50 - 250°C	n coefficient	SC method ^{*3} Upper : MD Lower : TD	8	0.2 8.5	1.0 6.3	0.4 8.1	1.0 6.2	-

Table 1 Properties of Sumikasuper® LCP

*1: Ratio of the molded article to the tool of $64mm \times 64mm \times 3mmt$

*2: The highest temperature at which the test piece does not deform after immersing into a solder bath for 60 sec.

*3: Test piece is the cut one of center portion of the test piece for tensile property.

Product Information

DuPont[™] Zenite[®] LCP

Liquid crystal polymer resin

PRELIMINARY DATA

Zenite[®] ZE17235 BK010 & NC010

35% Glass/Mineral Reinforced LCP Resin

Zenite® ZE17235 is a 35% glass/mineral reinforced Low Warp and High Flow LCP resin. It is well suited for use in the automotive, electrical/electronic, telecommunications and aerospace industries.

Property	Test Method	Units	Value
Mechanical			
Stress at Break	ISO 527-1/-2	MPa	130
Strain at Break	ISO 527-1/-2	%	1.80
Tensile Modulus	ISO 527-1/-2	MPa	11060
Flexural Strength	ISO 178	MPa	180
Flexural Modulus	ISO 178	MPa	13300
Notched Charpy Impact	ISO 180/1A	kJ/m ²	8.6
Thermal			
Deflection Temperature	ISO 75-1/-2	°C	285
1.80MPa			
Other			
Density	ISO 1183	Kg/m^3 (g/cm ³)	1690 (1.69)
Molding Shrinkage	ISO 294-4	%	
Normal			0.63
Parallel			0.17
Flammability			
UL 94 Rating at Min. Thickness	UL.94		V-0
UL 94 Min. Thickness Tested	UL94	mm	
Black			0.4
Natural			0.4
Processing		A CONTRACTOR OF	
Melt Temperature Range		°C	350-370
Mold Temperature Range		°C	30-95

Contact DuPont for Material Safety Data Sheet, general guides and/or additional information about ventilation, handling, purging, drying, etc. Mechanical properties measured at 23°C (73°F) unless otherwise stated.

Mechanical properties measured at 4.0mm unless otherwise stated.

Mold shrinkage measured at 2.0mm

During molding, use protective equipment and clothing. Skin contact with molten Zenite® resins can cause severe burns. Be particularly alert during purging.

The above data are preliminary and are subject to change as additional data are developed on subsequent lots.

Zenite® is a DuPont registered trademark. The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. This information may be subject to revision as new knowledge and experience becomes available. The data provided fall within the normal range of product properties and relate only to the specific material designated; these data may not be valid for such material used in combination with any other materials or in any process, unless expressly indicated otherwise. The data provided should not be used to establish specification limits or used alone as the basis of design, they are not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of a specific material aspecific material aspecific material aspecific material aspecific material aspecific material and substitute for any testing you may need to conduct to determine for yourself the suitability of a specific material aspecific material aspecific material for your particular purposes. Since DuPont cannot anticipate all variations in actual end-use conditions DuPont makes no warranties and assumes no liability in connection with any use of this information. Nothing in this publication is to be considered as a license to operate under or a recommendation to infinge any patent rights. Caution: Do not use this product in medical applications involving permanent implantation in the human body. For other medical applications see "DuPont Medical Caution Statement", H-51459 or H-50102.



The miracles of science*

		[] []					
QMFZ2 Component - Plastics		We	Wednesday, February 11, 2004	February	11, 200	4	E54705
SUMITOMO CHEMICAL CO LTD							
5-33 KITAHAWA 4-CHOME CHUO-KU OSAKA 541-6	541-8550 JP						
Material Designation: E6808UHF							
Product Description: Liquid Crystal Polymer (LCP),	(LCP), designated "SUMIKASUPER" furnished as pellets.	JPER" fur	nished as p	bellets.			
Color Min. Thick. (mm)	Flame HW	HWI HAI	RTI	RTI	RTI	ІЕС ӨМІТ	IEC GWFI
	Class		Elec	Imp	Str		
NC, BK 0.30	- 0-/	1	130	130	130	ī	T
CTI: - IEC CTI: -	HVTR: -		D495: -			IEC Ball Pressure (°C): -	
Dielectric Strength (k//mm): -	Volume Resistivity (10*ohm-cm): -	y (10 [×] ohm	- :(mɔ-			Dimensional Stability(%): -	
ISO Tensile Strength (MPa): -	ISO Flexural Strength (MPa): -	n gth (MPa	- :(ISO Heat Deflection (°C): -	
ISO Tensile Impact (kJ/m^2): -	ISO Izod Impact (kJ/m ²): -	(kJ/m ²): -				ISO Charpy Impact (kJ/m ²): -	
Report Date:	Underv	vriters Lab	Underwriters Laboratories Inc®	Inc®			
UL94 small-scale test data does not pertain to building materials, furnishings and related contents. UL 94 small-scale test data is intended solely for determining the	ding materials, furnishi	ngs and r	elated con	tents. UL	94 smal	l-scale test data is intended solely fo	- determining the
flammability of plastic materials used in components and parts of end-product devices and appliances, where the acceptability of the combination is determined by ULI.	s and parts of end-proc	luct device	es and appl	liances, w	there the	e acceptability of the combination is de	termined by ULI.

QMFZ2 C	component - Plastics	Tue	Tuesday, December 13, 2005 E106764					E106764		
POLYPLASTICS CO LTD										
VECTRA DIV 18-1 KONAN 2-CHOME MINATO-KU TOKYO 108-8280 JP										
Material Designation: E471i(d)										
Product Description: Liquid Crystal Polymer (LCP), designated "VECTRA" furnished as pellets.										
Color	Min. Thick.	Flame	HWI	HAI	RTI	RTI	RTI	IEC	IEC GWFI	
	(mm)	Class			Elec	Imp	Str	GWIT		
NC,	0.8	V-0	-	10	130	130	130	-	7	
BK										
ALL	1.5	V-0	-	÷	130	130	130	÷	-	
	3.0	V-0	17	-	130	130	130	÷	đ	
сті: 3	IEC CTI (V): -	HVTR:	-	IEC D495: -					Pressure (°C):	
								-		
Dielectri	c Strength							Dimensio	nal	
(kV/mm)	-	Volume	Resisti	vity (1)	0 [×] ohm-(cm): -		Stability(%): -		
ISO Ten	sile Strength (MPa):	ISO Flex						ISO Heat Deflection		
÷.		ISO Izo		600 5 0		93 		(°C): -		
ISO Ten	sile Impact (kJ/m ²):	150 120	a impu	ee (10/1				ISO Charpy Impact		
<i></i>								(kJ/m ²): -		
(d) Virgin and regrind up to 50% by weight incl. have the same basic material characteristics										
for colors NC and BK in the 0.75, 1.5 and 3.0 thickness.										
Report Date: 1/31/2000 Underwriters Laboratories Inc®										
UL94 small-scale test data does not pertain to building materials, furnishings and related contents.										
UL 94 small-scale test data is intended solely for determining the flammability of plastic materials										
used in o	omponents and parts	of end-pr	oduct d	evices	and app	pliance	s, whe	re the acce	ptability of the	
combination is determined by ULI.										

COPPER ALLOY SPECIFIC

Article	Standard NO	Dimension & Tempe
C2680	JIS H 3100	0.15mm X 16.5mm RH

	Chemocal Compositions (%)									
Element	Cu	Pb	Fe	Sn	Zn	Р	Ni	Mn	Mg	
Spec.	64~68	0.0500↓	0.05↓	—	REM	_	-	—	—	
Actual	65.21	0.0001	0.01	-	REM	_	-	_	_	

	Mechanical Properties.									
Item	Grain Size	Hardness	Tension Strength	Elongation	Electrical Conductivity	Bending Test	Surface Roughness	Camber		
Unit	mm	HV	Kgf/mm	%	% IACS	180 °	Ra(µm)	mm/1M		
Spec.	_	160~175	52~62	8↑	_	_	_	-		
Actual	_	164	53.9	16.3	_	_	_	_		

COPPER ALLOY SPECIFIC

Article	Standard NO	Dimension & Tempe
C5210	JIS H 3130	0.12mm X 16.5 mm SH

Chemocal Compositions (%)									
Element	Cu	Sn	Р	Zn	Fe	Pb			
Spec.	-	7.0~9.0	0.03~0.35	0.2↓	0.1↓	0.009↓			
Actual	92.11	7.52	0.0927	0.01	0.0089	0.003			

	Mechanical Properties.									
Item	Grain Size	Hardness	Tension Strength	Elongation	Electrical Conductivity	Bending Test	Surface Roughness	Camber		
Unit	mm	HV	Kgf/mm	%	% IACS	180 °	Ra(µm)	mm/1M		
Spec.	_	230~250	75~82	9↑	_	_	0.15↓	_		
Actual	—	238	76.8	14	13	Good	0.085	_		

FPC /FFC Connector Front Flip Lock Type Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's ZIF FPC/FFC connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's ZIF FPC/FFC connector, processing process product and processing product . Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please add a stiffener on the flexible printed circuit (FPC/FFC) when you mount the connector onto FPC in order to prevent deformation of the FPC/FFC.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

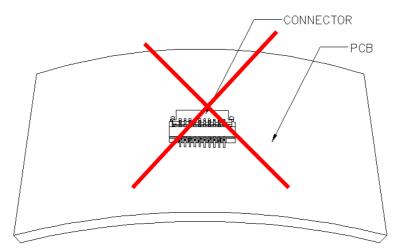
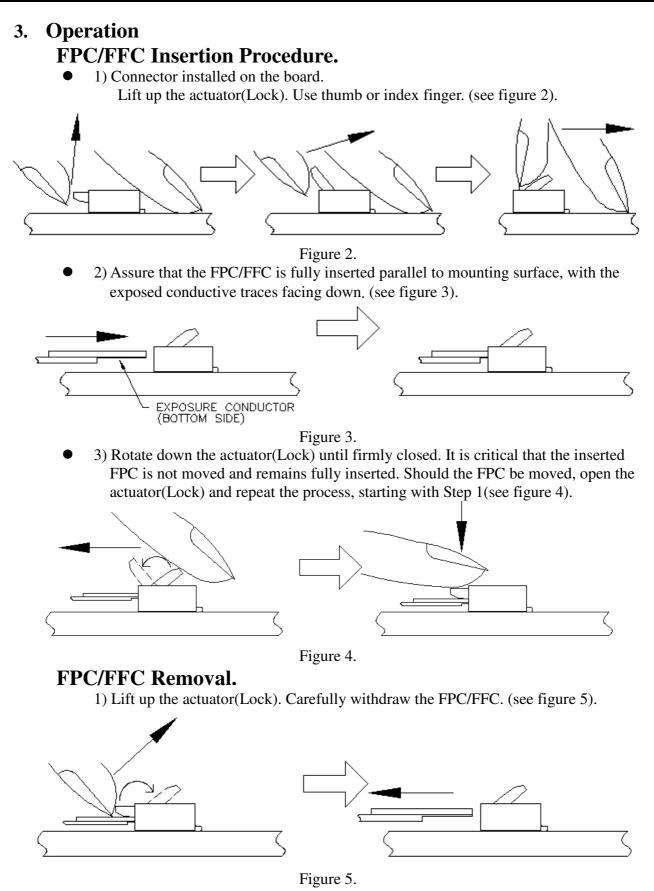


Figure 1.



4. Precautions When Inserting or Withdrawal FPC/FFC

• FPC/FFC to be insertion and withdrawal at an angle of about 15°, and the FPC/FFC should be inserted firmly all the way to the back. (see figure 6).

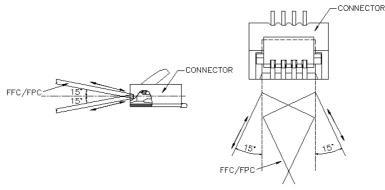


Figure 6.

- Do not apply excessive force or use any type of tool to operate the actuator(Lock).
- When locking the actuator(Lock), please make sure that the actuator is entirely closed by pressing on the entire actuator. Pushing the one specific point of the actuator may cause the actuator to be detached or damaged. When locking the longer actuator(Lock), please use two points to put pressure on locking. (see figure 7).

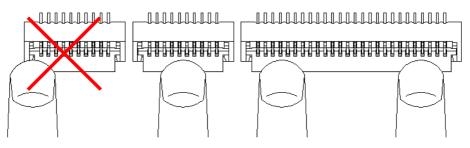
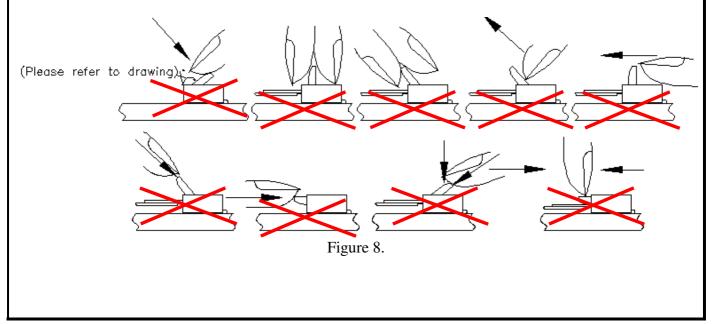
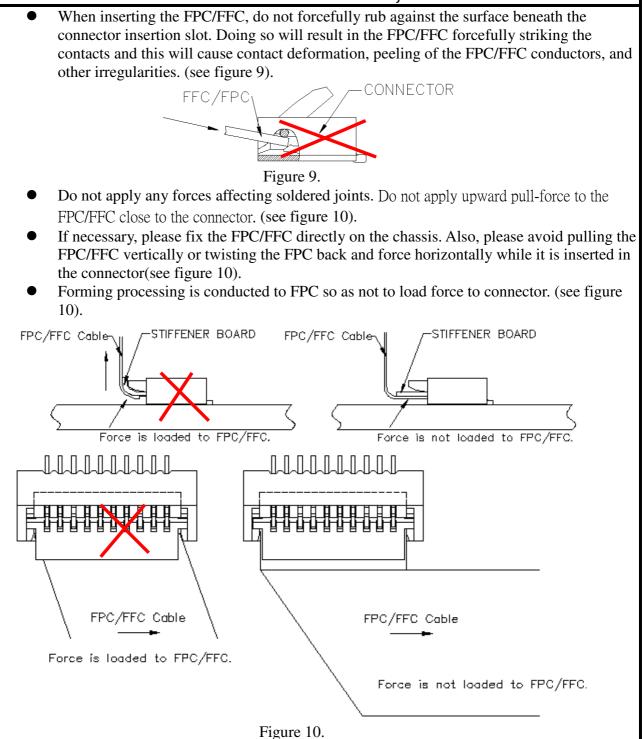


Figure 7.

- The connector will assure reliable performance when the actuator is open to an angle (please refer to drawing) maximum. Do not exceed this angle, as this may cause permanent damage to the connector. (see figure 8)
- Avoid grasping the actuator(Lock) with two fingers or lifting the actuator(Lock) with fingernail. (see figure 8)
- Do not apply force in the direction of arrows. Doing this may cause the actuator to be detached or damaged. (see figure 8).





ENTERY INDUSTRIAL CO., LTD. RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A0	First Release	JAN-27-2007	JOSH	First Release
A1	RE201108011	AUG-04-2011	JIMMY	ADD Handling Precautions
A2	RE201112022	JAN-04-2012	JIMMY	MODIFY COPPER ALLOY
A3	RE201204022	MAY-31-2012	JIMMY	MATERIAL CHANGE